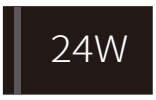
FEATURES

- 360W Peak Pulse Power per Line (tp=8/20μs)
- Protects one I/O line (unidirectional)
- Low clamping voltage
- Working voltages : 24V
- Low leakage current

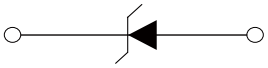
APPLICATIONS

- Cell Phone Handsets and Accessories
- Microprocessor based equipment
- Personal Digital Assistants (PDA' s)
- Notebooks, Desktops, and Servers
- Networking and Telecom
- Serial and Parallel Ports
- Peripherals

DFN1006



Marking



Schematic Symbol

IEC COMPATIBILITY

- IEC61000-4-2 (ESD) ±30kV (air), ±30kV (contact)
- IEC61000-4-4 (EFT) 40A (5/50ns)

APPROVALS

RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003

THERMAL CONSIDERATIONS

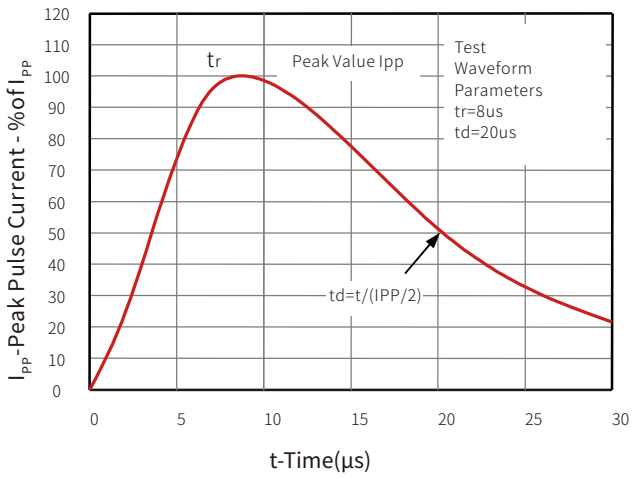
Symbol	Parameter	Value	Unit
P_{pp}	Peak Pulse Power (tp=8/20μs waveform)	360	Watts
T_J	Operating Temperature Range	-55 ~ +150	°C
T_{STG}	Storage Temperature Range	-55 ~ +150	°C

ELECTRICAL CHARACTERISTICS

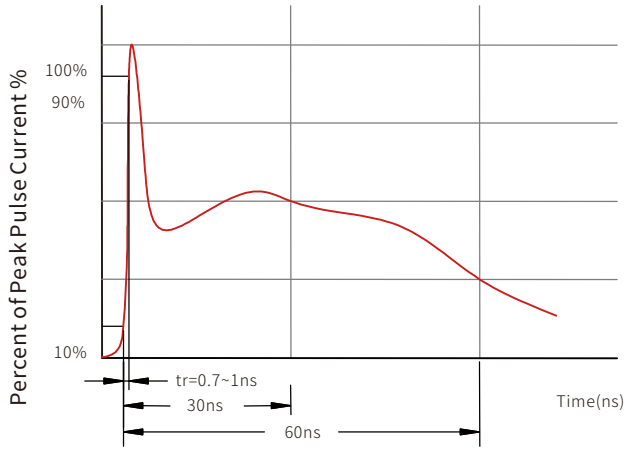
Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
V_{RWM}	Reverse Stand-off Voltage				24	V
V_{BR}	Reverse Breakdown Voltage	I_T=1mA	26.7			V
I_R	Reverse Leakage Current	V_{RWM}=24V			1	μA
V_C	Clamping Voltage	I_{PP}=1A,tp=8/20μs			43	V
V_C	Clamping Voltage	I_{PP}=8A,tp=8/20μs			45	V
I_{PP}	Peak Pulse Current	tp=8/20μs			8	A
C_J	Off State Junction Capacitance	V_R=0V, f=1MHz			80	pF

CHARACTERISTIC CURVES

8/20μs Pulse Waveform

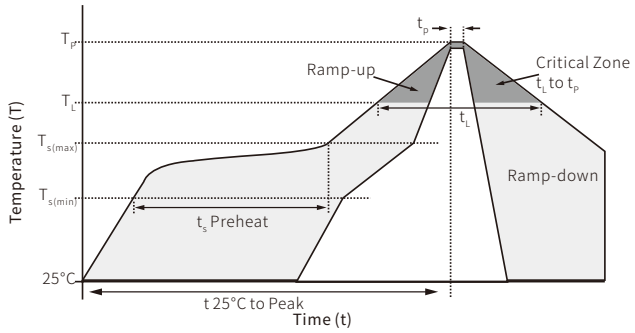


ESD Pulse Waveform (according to IEC 61000-4-2)

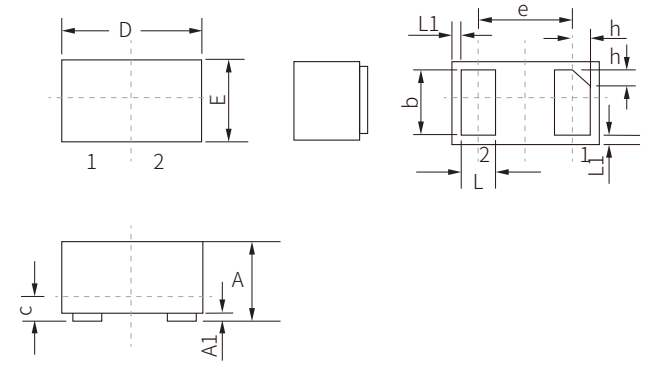


SOLDERING PARAMETERS

Reflow Condition		Lead–free assembly
Pre Heat	Temperature Max ($T_{s(min)}$)	150°C
	Temperature Max ($T_{s(max)}$)	200°C
	Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak		3°C/second max
$T_{S(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	Temperature (T_L) (Liquidus)	217°C
	Time (min to max) (t_L)	60 – 150 seconds
Peak Temperature (T_P)		260°C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_P)		8 minutes max.
Do not exceed		260°C

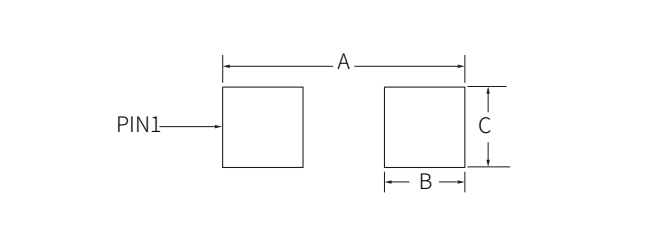


DFN1006 PACKAGE INFORMATION



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	0.40	0.60	0.016	0.024
A1	0	0.05	0	0.002
b	0.40	0.55	0.016	0.022
c	0.12	0.18	0.005	0.007
D	0.90	1.10	0.035	0.043
e	0.65BSC		0.026BSC	
E	0.55	0.75	0.022	0.030
L	0.20	0.35	0.008	0.014
L1	0.05REF		0.002REF	
h	0.07	0.17	0.003	0.007

RECOMMENDED PAD LAYOUT DIMENSIONS



Ref.	Millimeters	Inches
A	1.20	0.047
B	0.47	0.019
C	0.60	0.024

ORDERING INFORMATION

Part Number	Component Package	QTY/Reel	Reel Size
SE10F36U24A	DFN1006	10000PCS	7”

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